

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.35458	100.0	5.1
			<b>Subtotal</b>	<b>0.35458</b>	<b>100</b>	<b>5.1</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01037	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.16269	100.0	2.34
			<b>Subtotal</b>	<b>0.17306</b>	<b>200</b>	<b>2.4891</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73812	100.0	25
			<b>Subtotal</b>	<b>1.73812</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02336	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.0584	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.31893	99.86	838.824
			<b>Subtotal</b>	<b>58.40069</b>	<b>100</b>	<b>840</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.40236	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.25722	16.0	90
	Filler	Silica fused	60676-86-0	29.33071	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11732	0.3	1.6875
			<b>Subtotal</b>	<b>39.10761</b>	<b>100</b>	<b>562.5</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.0113	5.0	0.1625
	Lead alloy	Silver (Ag)	7440-22-4	0.00565	2.5	0.08125
	Lead alloy	Lead (Pb)	7439-92-1	0.20901	92.5	3.00625
			<b>Subtotal</b>	<b>0.22596</b>	<b>100</b>	<b>3.25</b>
			<b>Total</b>	<b>100.00002</b>	<b>100</b>	<b>1438.3391</b>

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